



3729

PATENT APPLICATION
Docket No. 9903-039
Client No. S01US029

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re application of: Seong-Jae Hong, et al.

Serial No. 10/036,983

Examiner: Nguyen, Donghai D

Confirmation No. 5318

Filed: December 31, 2001

Art Unit: 3729

For: UNDERFILL SYSTEM FOR SEMICONDUCTOR PACKAGE

Mail Stop Issue Fee
Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

RESPONSE TO INTERVIEW SUMMARY UNDER MPEP 713.04

Responsive to the Interview Summary, dated July 14, 2004, please accept the following statement regarding the substance of the telephonic interview between Examiner Donghai D. Nguyen and Hosoon Lee, on July 9, 2004.

No exhibits or demonstrations were conducted. Claims 1 and 9 were discussed. The Examiner and Applicant's Attorney were in agreement that the Examiner's Amendment places the application in condition for allowance, distinguishing over the Sterner (U.S. Pat. No. 6,253,834 B1) and Akram et al (U.S. Pat. No. 6,048,656) references. The Examiner prepared an Examiner's Amendment incorporating the changes agreed upon.

Respectfully submitted,

MARGER JOHNSON & McCOLLOM, P.C.

Hosoon Lee
Limited Recognition Under 37 CFR § 10.9(b)

MARGER JOHNSON & McCOLLOM, P.C.
1030 SW Morrison Street
Portland, OR 97205
503-222-3613

I hereby certify that this correspondence is being deposited with the United States Postal Service as first class mail in an envelope addressed to: Mail Stop Issue Fee Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450
Date: August 16, 2004

Adrienne Chocholak